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Abstract:

Semiconductor circuit module and method for fabricating semiconductor circuit modules

The present invention provides a method for fabricating semiconductor circuit modules (31) having the following steps: application of a patterned connection layer (11) to a transfer substrate (10); application of active circuit devices (12) and/or passive circuit devices (13) with contact areas (12', 13') pointing toward the transfer substrate (10) to the patterned connection layer (11); connection of the circuit devices (12, 13) to one another by means of a filler (14) at least between the circuit devices (12, 13); removal of the transfer substrate (10); and application of electrical connection devices (16) for selective contact-connection of the contact areas (12', 13') of the circuit devices (12, 13) to one another. The present invention likewise provides a semiconductor circuit module (31).

Figure 6A



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